

《阵列波导器件耦合封装机理及其关键》

图书基本信息

书名：《阵列波导器件耦合封装机理及其关键技术研究》

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作者：Zheng Yu

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内容概要

Arrayed wave guide devices are the foundations of the next generation optical fiber communication technology development, which have bright and wide application prospects. These arrayed waveguide chips, similar in many ways to their electronic counterparts, are fabricated using wafer-level processing techniques and use optical waveguides to route photons, the same way that metal traces are used to route electrons in an electronic chip. These devices include optical beam splitters/combiners for branching/ combining optical signals, optical switchers for changing optical paths, optical filtering for introducing multiple optical channels into a single optical fiber, and so on. These devices have many features, such as compact structure, strong noise immunity, excellent property, and easy automation production, which are the developing frontiers of optoelectronic devices at present. Arrayed waveguide devices are rich in their categories and structures. With the rapid increasing demands for the quality devices of optical fiber communication system, many problems about mechanisms and rules of manufacturing process for arrayed waveguide devices packaging must be investigated more profoundly, in order to make a breakthrough in the manufacturing technologies, processes and equipment of arrayed wave guide devices.

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作者简介

Zheng Yu, Central South University

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